



Power Options

Connect Power Supply to Vin

1. Operate using TPS62150 (default) 3-17V (4-8 Nominal)
 - Rim and rim1 should not be populated.
2. Operate using LM43601; 3.5-36V (4-8 Nominal)
 - Remove Rtps and Ltps1; populate Rim and Rim1

Ltps1 is a ferrite bead, if not used placed a 0 ohm resistor. it can be used at the output of the LM43601. Regulators should be enabled only one at a time.

On Board Oscillator Option

- Y1 and Y2 offers two standard footprint options

No solder mask below dap on bottom layer
Wider Vias on DAP TO Ground

Mechanical Information

PCB LOGO
ESD Susceptible
PCB LOGO
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